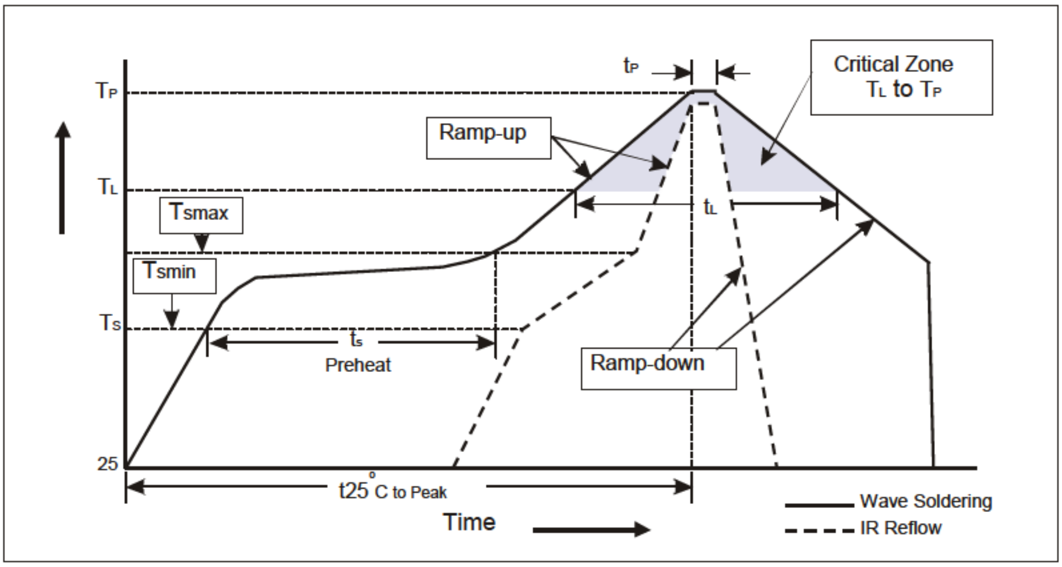
SMBJ Series (TVS Diode) Reflow Profile

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2.Reflow soldering of surface-mount devices



3.Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3 ℃/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	100 ℃ 150 ℃ 60~120sec
Tsmax to T_L -Ramp-upRate	<3 ℃/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	183 ℃ 60~150sec
Peak Temperature(T_P)	255 ℃-0/+5 ℃
Time within 5 C of actual Peak° Temperature(t_P)	10~30sec
Ramp-down Rate	<6 ℃/sec
Time 25℃ to Peak Temperature	<6 minutes